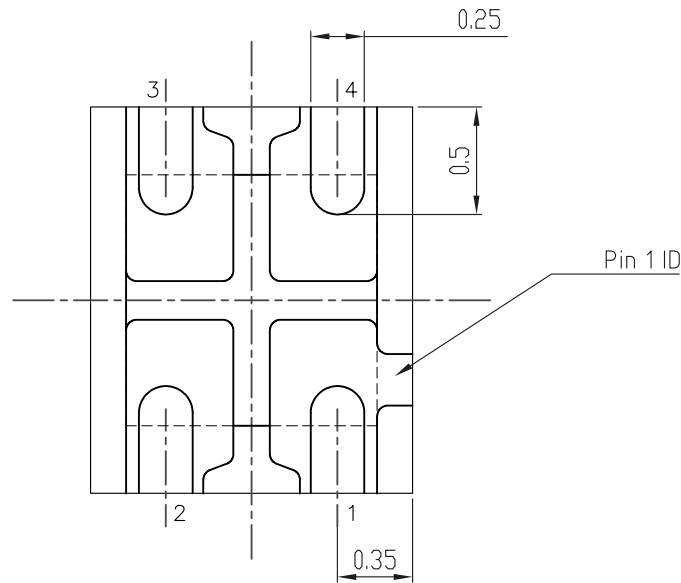
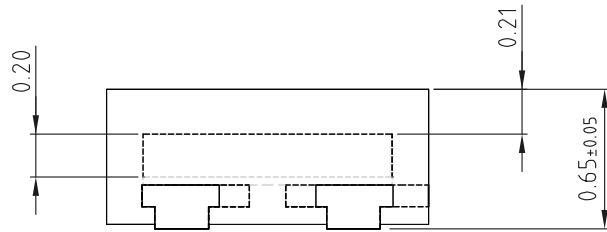


Pin Assignments	
Pin #	Description
1	Anode
2	Fast Output
3	Cathode
4	No Connect

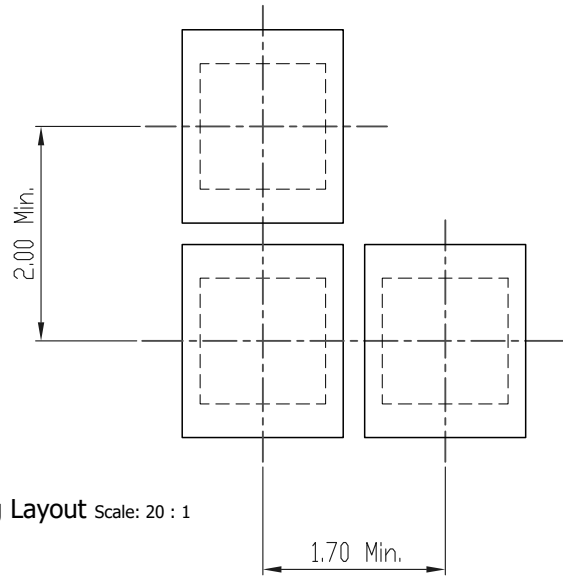
DATE	09 Feb 2017	REVISION	A	SCALE	Shown
SensL Technologies Ltd					Sheet
www.sensl.com					1 of 6
DWG. NO:	SND0204	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFR-100XX-MLP-C1					
PROJECTION					



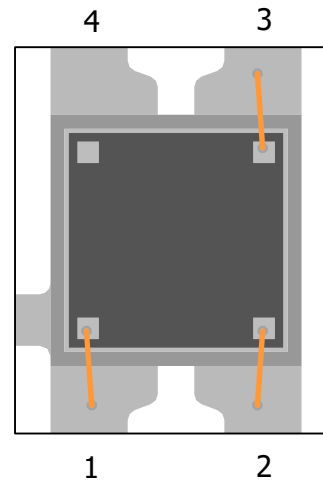
Bottom View Scale: 40 : 1

Pin Assignments	
Pin #	Description
1	Anode
2	Fast Output
3	Cathode
4	No Connect

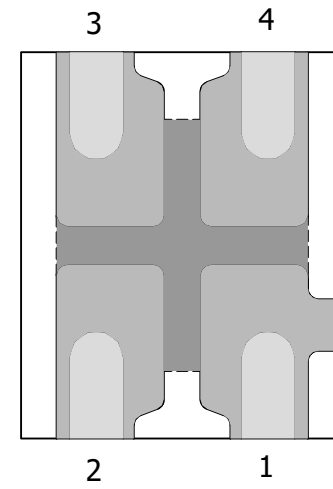
DATE	09 Feb 2017	REVISION	A	SCALE	Shown
SensL Technologies Ltd					Sheet
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DWG. NO:	SND0204	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFR-100XX-MLP-C1					
PROJECTION					



Tiling Layout Scale: 20 : 1



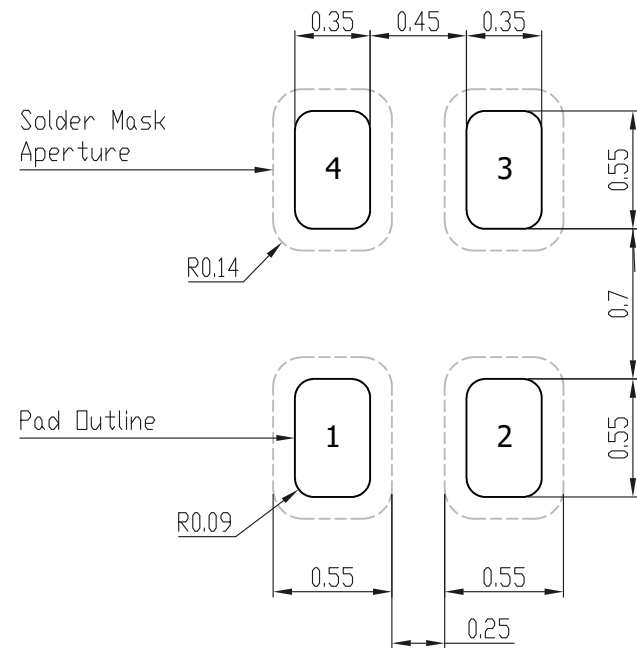
Top View Scale: 40 : 1



Bottom View Scale: 40 : 1

NOTE: Alignment and placement tolerances depend on the accuracy of the equipment used in the assembly process.

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SensL Technologies Ltd					Sheet
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DWG. NO:	SND0204	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFR-100XX-MLP-C1					
PROJECTION:					

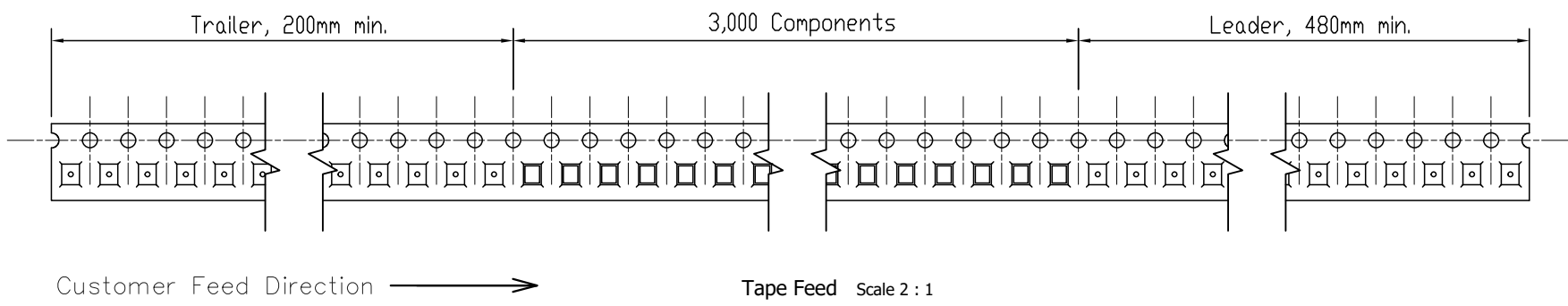
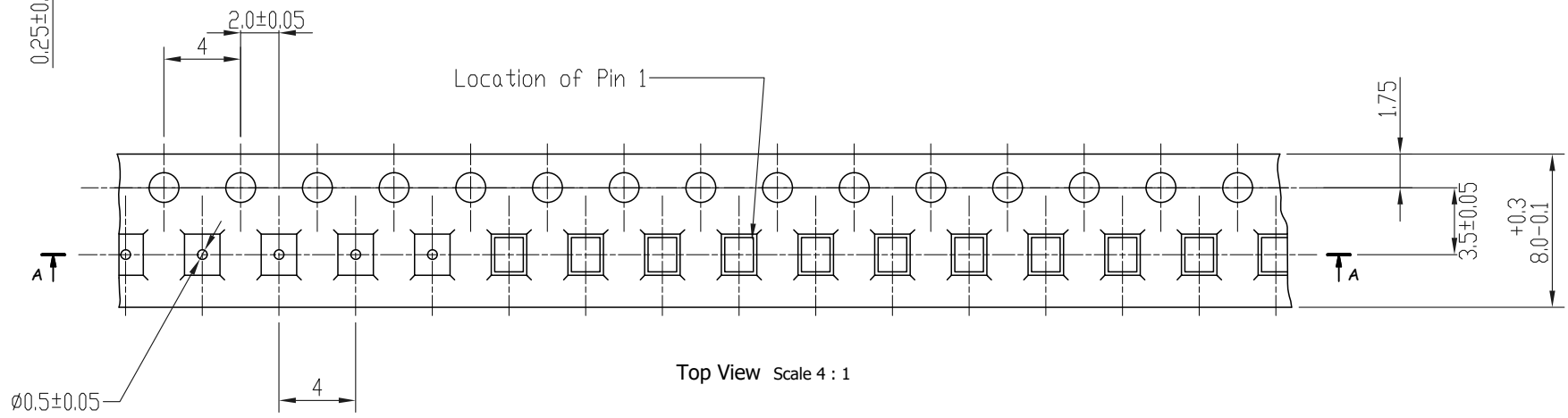
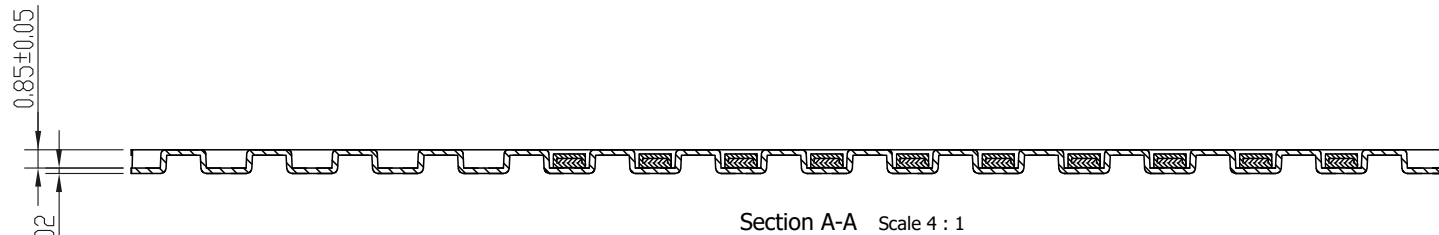


Recommended PCB Solder Footprint

Scale: 40 : 1

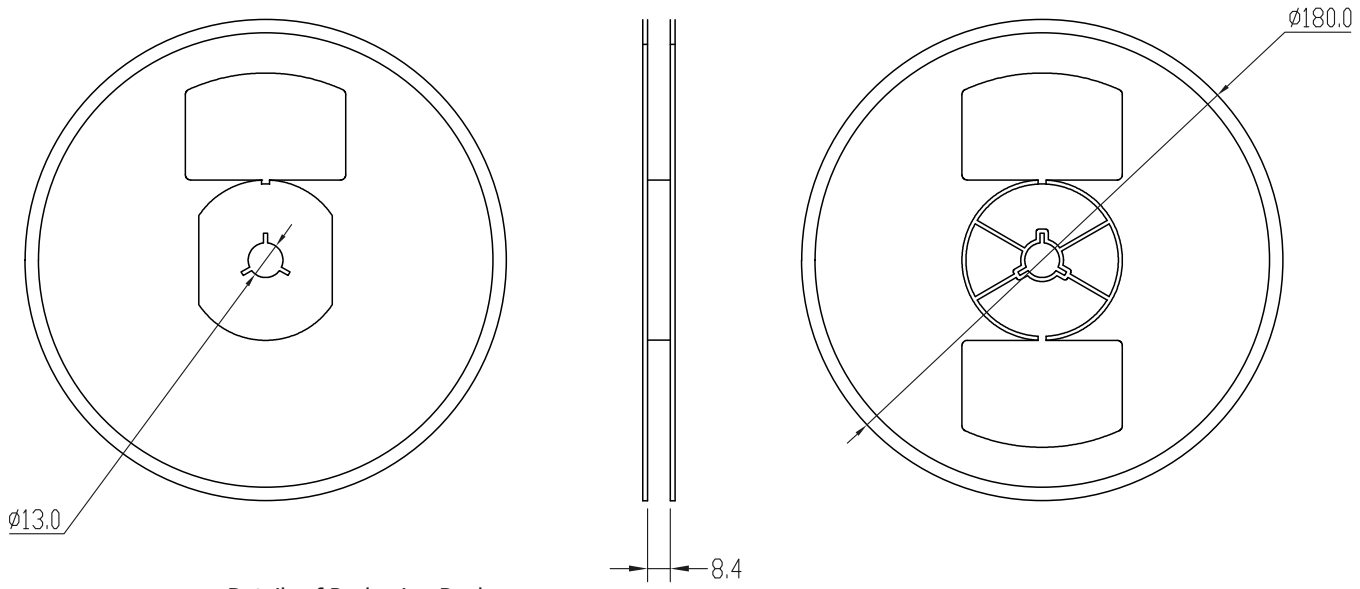
NOTE: No Connect (NC) pin 4 should be soldered to PCB, this pin can be connected to ground but it can also be left floating without affecting the dark noise.

DATE	09 Feb 2017	REVISION	A	SCALE:	Shown
SensL Technologies Ltd www.sensl.com				Sheet 4 of 6	
DWG. NO:	SND0204	DO NOT SCALE	ALL DIMENSIONS IN MM		
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PROJECTION:					



All Dimensions ± 0.1mm Unless Otherwise Stated

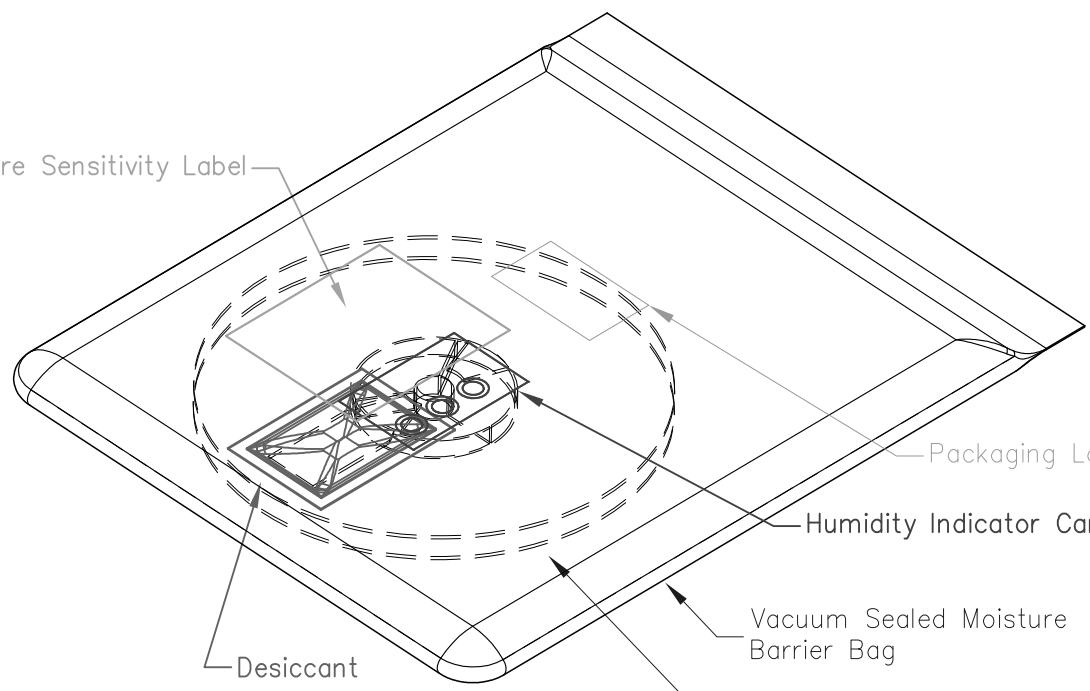
DATE	09 Feb 2017	REVISION	A	SCALE:	Shown
SensL Technologies Ltd				Sheet 5 of 6	
www.sensl.com					
DWG. NO:	SND0204	DO NOT SCALE ALL DIMENSIONS IN MM			
TITLE:					
MicroFR-100XX-MLP-C1					
PROJECTION:					



Details of Packaging Reel Scale 1 : 2

	<b>CAUTION</b>	<b>3</b>
	<b>MOISTURE SENSITIVE DEVICES</b>	
1. Calculated shelf life in sealed bag: 24 months at <math>+40^{\circ}\text{C}</math> and <math><90\%</math> relative humidity (RH)		
2. Peak package body temperature: <u>260</u> $^{\circ}\text{C}$ <small>If blank, see adjacent bar code label</small>		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be		
Mounted within: <u>168</u> hours of factory conditions <math><30^{\circ}\text{C}</math> @ 50% RH, or		
b) Stored per J-STD-033		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >50% for level 2 devices when read at 23 $\pm$ 5 $^{\circ}\text{C}$		
b) 3a or 3b are not met		
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: <u>20 Mar, 2014</u> <small>If blank, see adjacent bar code label</small>		
<small>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</small>		

Details of Moisture Sensitivity Label



5%	10%	60%
LEVEL2A-5A PARTS		LEVEL2 PARTS
<small>Bake if 10% IS NO BROWN and 5% IS AZURE</small>		<small>Bake Parts if 60%</small>
DOU YEE ENTERPRISES		IS NO BROWN
BROWN-DRY AXURE-WET		DO NOT
COBALT FREE HUMIDITY INDICATOR CARD		put this card into a
AVOID METAL CONTACT		bag if 5%, 10% or
COMPLIES WITH IPC/JEDEC J-STD-033		60%, and see above
		<b>H16 5 4 3 2 1</b>

Humidity Indicator Card

<b>sensl</b> <small>sense light</small>
<b>Part#: MicroFR-10035-MLP</b>
<b>Revision: C1</b>
<b>Lot#: E5678-35</b>
<b>Lot#:</b>
<b>Quantity: 3000</b>

Sample Packaging Label

DATE	09 Feb 2017	REVISION	A	SCALE:	Shown
SensL Technologies Ltd					Sheet
www.sensl.com					6 of 6
DWG. NO:	SND0204	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
<b>MicroFR-100XX-MLP-C1</b>					
PROJECTION:		<b>sensl</b> <small>sense light</small>			